

SLOVENSKI STANDARD**SIST EN 61192-5:2008****01-februar-2008**

Zahteve za izdelavo spajkanih elektronskih sestavov - 5. del: Nadaljnja obdelava, predelava in popravilo spajkanih elektronskih sestavov (IEC 61192-5:2007)

Workmanship requirements for soldered electronic assemblies - Part 5: Rework, modification and repair of soldered electronic assemblies

Anforderungen an die Ausführungsqualität von Lötabaugruppen - Teil 5: Nacharbeit, Änderungen und Reparatur von gelöteten elektronischen Baugruppen

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Exigences relatives a la qualité d'exécution des assemblages électroniques brasés - Partie 5: Retouche, modification et réparation des assemblages électroniques brasés

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**Workmanship requirements for soldered electronic assemblies -
Part 5: Rework, modification and repair of soldered electronic assemblies
(IEC 61192-5:2007)**

Exigences relatives à la qualité
d'exécution des assemblages
électroniques brasés -
Partie 5: Retouche, modification
et réparation des assemblages
électroniques brasés
(CEI 61192-5:2007)

Anforderungen an die Ausführungsqualität
von Lötabauprozessen -
Teil 5: Nacharbeit, Änderungen
und Reparatur von gelöteten
elektronischen Baugruppen
(IEC 61192-5:2007)

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This European Standard was approved by CENELEC on 2007-06-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.
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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 91/652/FDIS, future edition 1 of IEC 61192-5, prepared by IEC TC 91, Electronics assembly technology, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 61192-5 on 2007-06-01.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2008-03-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2010-06-01

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 61192-5:2007 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

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IEC 61760-1	NOTE	Harmonized as EN 61760-1:2006 (not modified).
ISO 9000	NOTE	Harmonized as EN ISO 9000:2005 (not modified).
ISO 9001	NOTE	Harmonized as EN ISO 9001:2000 (not modified).
ISO 9453	NOTE	Harmonized as EN ISO 9453:2006 (not modified). http://standards.itech.ai/standard/iso/iso9453:2006/f11174:87199-288a531e7eda/sist-en-61192-5-2008
ISO 9454-1	NOTE	Harmonized as EN 29454-1:2003 (not modified).

Annex ZA

(normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	- ¹⁾	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	2006 ²⁾
IEC 61190-1-1	- ¹⁾	Attachment materials for electronic assembly - Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly	EN 61190-1-1	2002 ²⁾
IEC 61190-1-2	- ¹⁾	Attachment materials for electronic assembly - Part 1-2: Requirements for soldering paste for high-quality interconnects in electronics assembly SIST EN 61192-5:2008	EN 61190-1-2	2007
IEC 61190-1-3	- ¹⁾	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications	EN 61190-1-3	2007
IEC 61191-1	1998	Printed board assemblies - Part 1: Generic specification - Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies	EN 61191-1	1998
IEC 61191-2	1998	Printed board assemblies - Part 2: Sectional specification - Requirements for surface mount soldered assemblies	EN 61191-2	1998
IEC 61191-3	- ¹⁾	Printed board assemblies - Part 3: Sectional specification - Requirements for through-hole mount soldered assemblies	EN 61191-3	1998 ²⁾

¹⁾ Undated reference.

²⁾ Valid edition at date of issue.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61191-4	- ¹⁾	Printed board assemblies - Part 4: Sectional specification - Requirements for terminal soldered assemblies	EN 61191-4	1998 ²⁾
IEC 61192-1	- ¹⁾	Workmanship requirements for soldered electronic assemblies - Part 1: General	EN 61192-1	2003 ²⁾
IEC 61192-2	- ¹⁾	Workmanship requirements for soldered electronic assemblies - Part 2: Surface-mount assemblies	EN 61192-2	2003 ²⁾
IEC 61192-3	- ¹⁾	Workmanship requirements for soldered electronic assemblies - Part 3: Through-hole mount assemblies	EN 61192-3	2003 ²⁾
IEC 61192-4	- ¹⁾	Workmanship requirements for soldered electronic assemblies - Part 4: Terminal assemblies	EN 61192-4	2003 ²⁾
IEC 61193-1	- ¹⁾	Quality assessment systems - Part 1: Registration and analysis of defects on printed board assemblies	EN 61193-1	2002 ²⁾
IEC 61249	Series	Materials for printed boards and other interconnecting structures	EN 61249	Series

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INTERNATIONAL STANDARD

IEC
61192-5

First edition
2007-05

Workmanship requirements for soldered electronic assemblies –

Part 5:
Rework, modification and repair
of soldered electronic assemblies
iTECH STANDARD REVIEW
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Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

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CONTENTS

FOREWORD	5
1 Scope	7
2 Normative references	8
3 Terminology	9
3.1 Terms and definitions	9
3.2 Abbreviations	9
4 Classification of rework activities	10
4.1 Pre-soldering rework	10
4.2 Post-soldering rework	10
4.3 Essential prerequisites for successful and reliable rework	10
5 Pre-soldering rework	11
5.1 General	11
5.2 Reworking solder paste and non-conducting adhesive deposits	11
5.2.1 General	11
5.2.2 General misalignment or smudging of deposits	11
5.2.3 Local misalignment or smudging of deposit	11
5.2.4 General paste or adhesive quantity incorrect	12
5.2.5 Local paste or adhesive quantity incorrect	12
5.3 Reworking placed components	12
5.3.1 General overall component misalignment	12
5.3.2 Local component misalignment	12
5.4 Realigning components after curing thermoplastic adhesive	12
5.5 Realigning components after curing thermosetting adhesive	12
6 Factors affecting post-soldering rework	13
6.1 Component marking and unmarked components	13
6.2 Reuse of removed components	13
6.3 Sensitive components	13
6.4 Printed board layout design and space constraints	14
6.5 Heat-sink effects	14
6.6 Printed board material type	14
6.7 Solder resist material and aperture size	15
6.8 Reworking individual fine pitch device leads	16
6.9 Reworking grid arrays	16
7 Preparation for post-soldering rework and repair	17
7.1 Electrostatic precautions	17
7.2 Avoiding exposure of components to contaminants	17
7.3 Removal of conformal coating	17
7.4 Unsuitable components	18
7.5 Cleaning prior to rework	18
7.6 Protecting adjacent sensitive components	18
7.7 Baking of assemblies prior to component replacement	18
7.8 Preheating large multilayer boards	18
7.9 Preheating replacement sensitive components	18
8 Post-soldering rework	19
8.1 General	19

8.2	Component realignment (tweaking)	19
8.3	Component removal	19
8.4	Removal of adjacent components	19
8.5	Reuse of components	19
8.6	Addition of flux and solder	20
8.7	Topping-up	20
8.8	Removal of excess solder from joints	21
8.9	Preparation of lands before component replacement	21
8.10	Component replacement	22
8.11	Cleaning (if required)	22
8.12	Visual inspection and electrical testing	22
8.13	Checking thermal integrity of solder joints	22
8.14	Replacement of local conformal coating (if required)	22
9	Selection of rework equipment, tools and methods	22
9.1	General	22
9.2	Matching rework equipment to component and printed-board prerequisites	23
9.2.1	General	23
9.2.2	Selection based on component types on the printed board	24
9.2.3	Selection based on printed-board laminate material type	24
9.2.4	Selection based on assembly structure and soldering processes	24
10	Manual rework tools and methods	26
10.1	General	26
10.2	Miniature conventional (stored energy) soldering irons	26
10.3	Directly heated soldering irons	27
10.4	Hot air/gas pencils	28
10.5	Heated tweezers	28
10.6	Soldering irons with special tips	29
11	Mechanized and programmable rework machines	29
11.1	General	29
11.2	Hot air rework machines	29
11.3	Focused infrared (IR) equipment	30
11.4	Thermode (heated electrode) equipment	31
11.5	Laser equipment for de-soldering	32
12	Ancillary tools and equipment	33
12.1	Conventional soldering irons	33
12.2	Hotplates	33
12.3	Pneumatic dispensers	33
12.4	De-soldering tools, as used for through-hole assemblies	34
12.5	Tweezers and vacuum pencils	34
12.6	Solder pots	34
12.7	Copper braid	34
13	Rework recording procedures	34
13.1	General	34
13.2	Anomaly charts	34
13.3	Travelling documents	35
13.4	Rework status	36
14	Training of operators and inspectors	36
15	Field repair	37

Bibliography.....	38
Figure 1 – Typical in-process modification, rework or repair activities	7
Figure 2 – Gang mounting no solder mask between lands.....	15
Figure 3 – Conductor between lands on small pitch	15
Figure 4 – Optional solder-mask design for multiple termination component attachment.....	16
Figure 5 – SOIC repair procedure example	23
Figure 6 – Comparing hot air/gas and infrared rework processes	26
Figure 7 – Miniature conventional soldering iron	27
Figure 8 – Hot air solder system	30
Figure 9 – Heated thermode reflow soldering.....	31
Figure 10 – Automated laser reflow equipment	33
Table 1 – Recommended tools for different component types	25
Table 2 – Electrical and electronic assembly defects	35

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[SIST EN 61192-5:2008](#)

<https://standards.iteh.ai/catalog/standards/sist/a46128af-1dd7-4e87-bf99-288a531e7eda/sist-en-61192-5-2008>

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**WORKMANSHIP REQUIREMENTS FOR
SOLDERED ELECTRONIC ASSEMBLIES –****Part 5: Rework, modification and repair of
soldered electronic assemblies****FOREWORD**

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International Standard IEC 61192-5 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/652/FDIS	91/686/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61192 series, under the general title *Workmanship requirements for soldered electronic assemblies*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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WORKMANSHIP REQUIREMENTS FOR SOLDERED ELECTRONIC ASSEMBLIES –

Part 5: Rework, modification and repair of soldered electronic assemblies

1 Scope

This part of IEC 61192 provides information and requirements that are applicable to modification, rework and repair procedures for soldered electronic assemblies. It is applicable to specific processes used to manufacture soldered electronic assemblies where components are attached to printed boards and to the relevant parts of resulting products. The standard is also applicable to activities that can form part of the work in assembling mixed technology products.

This part of IEC 61192 also contains guidance on design matters where they have relevance to rework.

NOTE Typical in-process surface-mount rework activities to which this standard applies are shown in Figure 1.

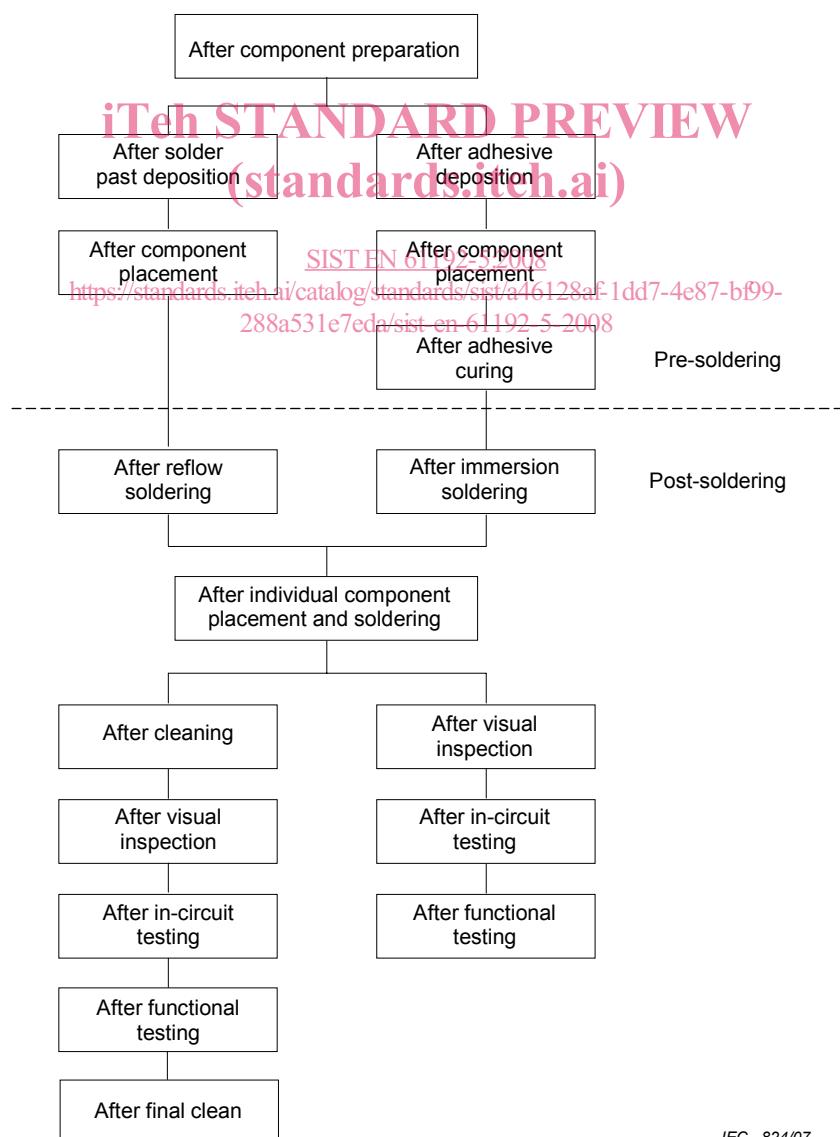


Figure 1 – Typical in-process modification, rework or repair activities